

NEGATIVE PHOTOSENSITIVE RESIN COMPOSITION, NEGATIVE PHOTOSENSITIVE RESIN COMPOSITION COATING FILM, NEGATIVE PHOTOSENSITIVE RESIN COMPOSITION FILM, CURED FILM, AND ELECTRONIC COMPONENT COMPRISING SAME

ABSTRACT

The present invention provides a resin composition which has excellent pattern processability in a thick film and does not generate an organic deposit even when processing is performed on a substrate having an aluminum pad electrode. A negative photosensitive resin composition contains (B) a polymerizable compound and (C) a photopolymerization initiator. The content of fluorine atoms in the total solid content of the negative photosensitive resin composition is characterized to be 0.0% by mass to 1.0% by mass inclusive.

No suitable figure